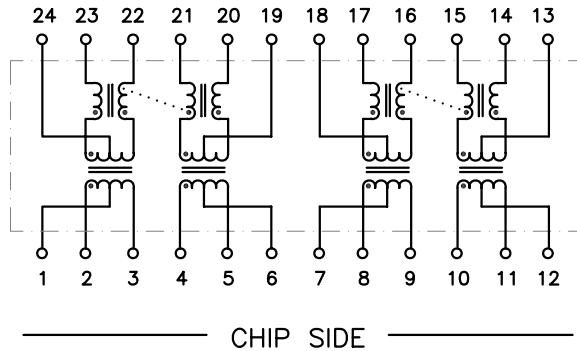


DIMENSIONS: Inch [mm]  
CO-PLANARITY: 0.004 [0.10]  
TOLERANCES: ±0.005 INCH IF NOT SPECIFIED



CHIP SIDE

## PART NO. : TG110-RP01NZRL

DUAL-PORT FAST OR SINGLE GIGABIT ETHERNET  
COMPLIANT WITH IEEE802.3af REQUIREMENTS  
350mA DC CURRENT CARRYING CAPACITY  
ON LINE SIDE FOR PoE APPLICATIONS  
RoHS COMPLIANT  
COMPATIBLE TO LEAD-FREE SOLDERING PROCESS  
CONDITION PER IPC/JEDEC J-STD-020C  
OPERATING TEMPERATURE 0/+70°C

## ELECTRICAL SPECIFICATIONS @25° C

URNS RATIO	1CT:1CT ±2%
OCL (100KHz,0.1Vrms,8mA)	350µH min
DCR (CHIP SIDE)	0.9Ω max
INSERTION LOSS	
1-100MHz	-1.1dB max
RETURN LOSS	
1-40MHz	-18dB min
60MHz	-14dB min
80MHz	-12dB min
100MHz	-10dB min
CROSSTALK	
1-100MHz	-38dB typ
CMR	
1-100MHz	-38dB typ
ISOLATION	1,500Vrms



**HALO/PBL**

CALIFORNIA, USA  
KOWLOON, HONG KONG  
SINGAPORE

TITLE	ISOLATION MODULE		SIGNATURES	DATE	REV.	DESC.	DATE
FOR	FAST/GIGABIT ETHERNET, PoE		DRAWN	PETER LU	11/22/05	A	FIRST ISSUE
PART NO.	TG110-RP01NZRL		CHECKED	LEI KEONG	2/15/06	B	PROD. RELEASE
SCALE	NONE	PAGE	1 OF 1		APPROVED	PETER LU	2/15/06
			FILE	RP01NZRL.DWG			